

PATENT APPLICATION TRANSMITTAL LETTER
(Large Entity)

Docket No.
MICT-0050-US (99-0325)

TO THE ASSISTANT COMMISSIONER FOR PATENTS

Transmitted herewith for filing under 35 U.S.C. 111 and 37 C.F.R. 1.53 is the patent application of:

D. Rumsey

For: **Positioning Flowable Solder for Bonding Integrated Circuit Elements**

Enclosed are:

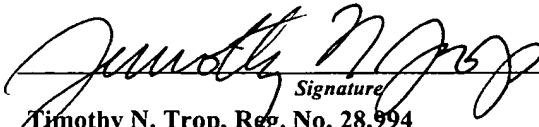
- ☒ Certificate of Mailing with Express Mail Mailing Label No. **EL360180020US**
- ☒ 2 sheets of drawings.
- ☐ A certified copy of a application.
- ☒ Declaration ☒ Signed. ☐ Unsigned.
- ☒ Power of Attorney
- ☐ Information Disclosure Statement
- ☐ Preliminary Amendment
- ☒ Other: **Recordation Form Cover Sheet and Assignment**

CLAIMS AS FILED

For	#Filed	#Allowed	#Extra	Rate	Fee
Total Claims	30	- 20 =	10	x \$18.00	\$180.00
Indep. Claims	4	- 3 =	1	x \$78.00	\$78.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
BASIC FEE					\$760.00
TOTAL FILING FEE					\$1,018.00

- ☒ A check in the amount of **\$1,018.00** to cover the filing fee is enclosed.
- ☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. **20-1504** as described below. A duplicate copy of this sheet is enclosed.
 - ☐ Charge the amount of as filing fee.
 - ☒ Credit any overpayment.
 - ☒ Charge any additional filing fees required under 37 C.F.R. 1.16 and 1.17.
 - ☐ Charge the issue fee set in 37 C.F.R. 1.18 at the mailing of the Notice of Allowance, pursuant to 37 C.F.R. 1.311(b).

Dated: 8/18/99


Signature
Timothy N. Trop, Reg. No. 28,994
Trop, Pruner, Hu & Miles, P.C.
8554 Katy Freeway, Suite 100
Houston, TX 77024
(713) 468-8880 [Ph]
(713) 468-8883 [Fax]

cc: